WHAT IS CLAIMED IS:

1. A packaging process comprising steps of:

providing a first carrier;

forming a first thermal release material on the first carrier;

providing at least one electronic component and at least one thermal conduction structure attached on the first thermal release material, wherein the at least one electronic component comprises at least one conducting terminal;

forming a first insulation layer on a first surface of the electronic component and a first surface of the thermal conduction structure;

removing the first carrier and the first thermal release material;

providing a second carrier;

forming a second thermal release material on the second carrier;

attaching the first insulation layer with the electronic component and the thermal conduction structure on the second thermal release material;

grinding at least one of a portion of a second surface of the electronic component, a portion of a second surface of the thermal conduction structure, and a portion of the first insulation layer;

forming a second insulation layer on the second surface of the electronic component and the second surface of the thermal conduction structure;

removing the second carrier and the second thermal release material;

forming plural first openings on the first insulation layer;

forming plural second openings through the corresponding first openings, wherein the conducting terminal and the first surface of the thermal conduction structure are exposed through the plural second openings;

forming a first metal layer through the plural second openings and disposed on the conducting terminal and the first surface of the thermal conduction structure;

forming plural third openings on the second insulation layer;

forming plural fourth openings through the plural third openings, wherein the second surface of the thermal conduction structure is exposed through the fourth opening;

forming a second metal layer through the plural fourth openings and disposed on the second surface of the thermal conduction structure;

grinding a portion of the first metal layer to form at least one first contact pad and at least one second contact pad; and

grinding a portion of the second metal layer to form at least one third contact pad.

2. The packaging process according to claim 1, wherein the at least one first contact pad is corresponding to and in contact with the conducting terminal of the electronic component, the at least one second contact pad is corresponding to and in contact with the first surface of the thermal conduction structure, and the at least one third contact pad is corresponding to and in contact with the second surface of the thermal conduction structure.

3. The packaging process according to claim 1, wherein the packaging process further comprises steps:

forming a first passivation layer on at least portion of the at least one first contact pad and a portion of the at least one second contact pad; and

forming a second passivation layer on a portion of the at least one third contact pad, wherein a portion of the at least one second contact pad uncovered by the first passivation layer is exposed, and a portion of the at least one third contact pad uncovered by the second passivation layer is exposed.

4. The packaging process according to claim 3, wherein the packaging process further comprises a step:

providing a passive component on the first passivation layer, wherein a portion of the passive component is coupled with the at least one second contact pad.

5. The packaging process according to claim 3, wherein the packaging process further comprises a step:

providing a board on the second passivation layer, wherein the board is coupled with the at least one third contact pad.

6. The packaging process according to claim 3, wherein at least one of the first passivation layer and the second passivation layer comprises at least one of a resin, an insulation material, and a combination thereof.

7. The packaging process according to claim 1, wherein at least one of the first insulation layer and the second insulation layer comprises at least one of a resin, an Ajinomoto build-up film, and a combination thereof.

8. The packaging process according to claim 1, wherein the at least one conducting terminal of the at least one electronic component is disposed on the first surface of the at least one electronic component.

9. The packaging process according to claim 1, wherein plural thermal conduction structures are provided, wherein the at least one electronic component is disposed between or encompassed by the plural thermal conduction structures.

10. The packaging process according to claim 9, wherein plural electronic components are provided, wherein the plural electronic components are disposed between the plural thermal conduction structures.

11. The packaging process according to claim 1, wherein the electronic component is grinded till a specific thickness of the electronic component is obtained, wherein the specific thickness of the electronic component is less than or equal to 50μm.

12. The packaging process according to claim 1, wherein at least one of the first metal layer and the second metal layer comprises copper or copper-containing material.

13. The packaging process according to claim 1, wherein at least one of the plural first openings, the plural second openings, the plural third openings, and the plural fourth openings is formed by a drilling process.